



Customer Information Notification

2023080081 : MC33972 and MC33975 Data Sheet Updates (Technical Clarifications / Corrections)

Note: This notice is NXP Company Proprietary.

Issue Date: Sep 07, 2023 **Effective date:** Sep 08, 2023

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Change Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Process	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Location	<input type="checkbox"/> Electrical spec./Test coverage
<input type="checkbox"/> Firmware	<input checked="" type="checkbox"/> Other: Data Sheet Update (Technical Clarifications / Corrections)			

PCN Overview

Description

NXP Semiconductors announces data sheet updates for the MC33972 and MC33975 (MSDI - Multiple Switch Detection Interface with Suppressed Wake-up) products associated with this notification. New MC33972 data sheet revision 20.0 and new MC33975 data sheet revision 12.0 are now available. Please see the revision history included in the updated documents for a detailed description of the changes.

**** Documentation update only - absolutely no change to product or materials ****

Correct the data sheet package drawing referenced to 98ASA00259D Rev B, which includes etched leadframe package representation.

New MC33972 revision 20.0 data sheet is attached to this notice and can be accessed at:
<https://www.nxp.com/docs/en/data-sheet/MC33972.pdf>

New MC33975 revision 12.0 data sheet is attached to this notice and can be accessed at:
<https://www.nxp.com/docs/en/data-sheet/MC33975.pdf>

Corresponding ZVEI Delta Qualification Matrix ID: SEM-DS-02

Reason

The data sheets have been updated for technical clarifications and corrections - to correct the data sheet package drawing referenced to 98ASA00259D Rev B, which includes etched leadframe package representation.

Identification of Affected Products

Product identification does not change

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision

A new datasheet will be issued

Additional information

Additional documents: [view online](#)

Related Notification

Notification	Issue Date	Effective Date	Title
202305031F01	May 25, 2023	Aug 23, 2023	SOIC 32LD Exposed Pad Stamped Leadframe Qualification

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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NXP Quality Management Team.

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Orderable Part Number#	12NC	Product Type	Product Description	Package Outline	Package Description	Product Status	Customer Specific Indicator	Product Line
MC33972ATEK	935310397574	MC33972ATEK	MULT SW DET SUP-WKUP	SSOP32	SOT1762-2	RFS	No	BLC4
MC33972ATEKR2	935310397518	MC33972ATEKR2	MULT SW DET SUP-WKUP	SSOP32	SOT1762-2	RFS	No	BLC4
MC33972TEW	935318405574	MC33972TEW	MULTI-SW DETECT W/SUPRES	SSOP32	SOT1762-1	RFS	No	BLC4
MC33972TEWR2	935318405518	MC33972TEWR2	MULTI-SW DETECT W/SUPRES	SSOP32	SOT1762-1	RFS	No	BLC4
MC33972ATEW	935310479574	MC33972ATEW	MULT SW DET SUP-WKUP	SSOP32	SOT1762-1	RFS	No	BLC4
MC33972ATEWR2	935310479518	MC33972ATEWR2	MULT SW DET SUP-WKUP	SSOP32	SOT1762-1	RFS	No	BLC4
MC33975ATEK	935311836574	MC33975ATEK	ENHANCED MULTI SW DETECT	SSOP32	SOT1762-2	RFS	No	BLC4
MC33975ATEKR2	935311836518	MC33975ATEKR2	ENHANCED MULTI SW DETECT	SSOP32	SOT1762-2	RFS	No	BLC4
MC33975TEK	935315721574	MC33975TEK	MULTI SW DETECT INTERFAC	SSOP32	SOT1762-2	RFS	No	BLC4
MC33975TEKR2	935315721518	MC33975TEKR2	MULTI SW DETECT INTERFAC	SSOP32	SOT1762-2	RFS	No	BLC4